

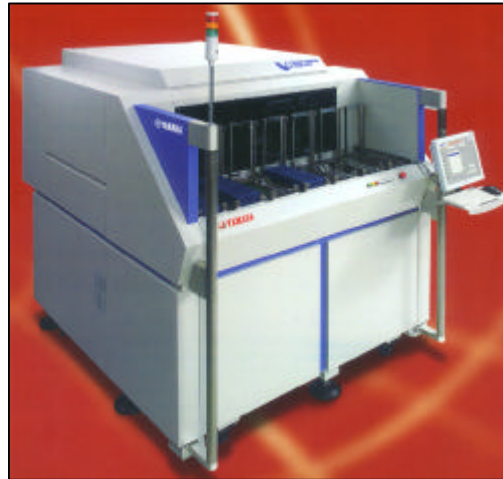
## System Specifications

### FULL VISION IC Handler V4

This handler is High throughput, full Vision Model and concentrated the latest technology of YAMAHA/I-Pulse.

#### Feature

- ✦ Highly accurate contact  
XY  $\pm 40 \mu\text{m}$  =  $\pm 0.2^\circ$
- ✦ High throughput  
Four site simultaneous measurement, high speed index
- ✦ Less need of change kit  
Less need of pocket for alignment
- ✦ Occurrence of jamming reduced sharply  
Less stress applied to devices



#### Specifications V4

Item	Standard	Option
Applicable devices	BGA,CSP,WLCSP,QFN,LCC	QFP
Applicable package size	1.5mm ~ 20mm Minimum bump pitch:0.3mm Minimum bump pitch diameter:0.16mm	1.5mm ~ 40mm Minimum bump pitch:0.5mm Minimum bump pitch diameter:0.3mm
No. of IC's measured in parallel	1,2,4	
Pitch between sockets	60mm? 80mm (square 4-site)	
Contact method	Non-drop pressure contact method or drop pressure contact method	
Alignment of devices	Positioning correction by image recognition	
Measurement temperature	Ordinary temperature	+50 ~ +125 $\pm 3$ Hot plate type
Test head area	1,200mm head accommodate	
Supply & storage of devices	Tray	
Device infeed method	1 units of auto tray	
Device outfeed method	2 units of auto tray	5 units of auto tray
No. of categories	2	Up to 5
Tray supply quantity	H300mm $\times$ 1 units	
Tray capacity	H300mm $\times$ 2 units	H300mm $\times$ 5 units
Tray size	JEDEC	
Index time	Less than 0.5 sec. at shortest	
Throughput	Up to 5,000 UPH (ordinary temperature, 4pcs in parallel measurement)	Up to 8,000 UPH (ordinary temperature, 4pcs in parallel measurement, with high speed camera)
Dimensions	W1640mm $\times$ D1970mm $\times$ H1745 (excluding tower light)	
Weight	1400kg(provided with casters)	

*About this system, please contact us.*

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